



Heatsinks f.cool

- ▶ Profile heatsinks and fluid coolers
- ▶ Heatsinks and active heatsinks for processors
- ▼ Board Level heatsinks
 - Finger shaped heatsinks
 - Attachable heatsink
 - Small heatsinks
 - Heatsinks for D PAK and others
- ▶ Cooling aggregates
- ▶ Accessories for electronic components

Cases f.case

Connectors f.con

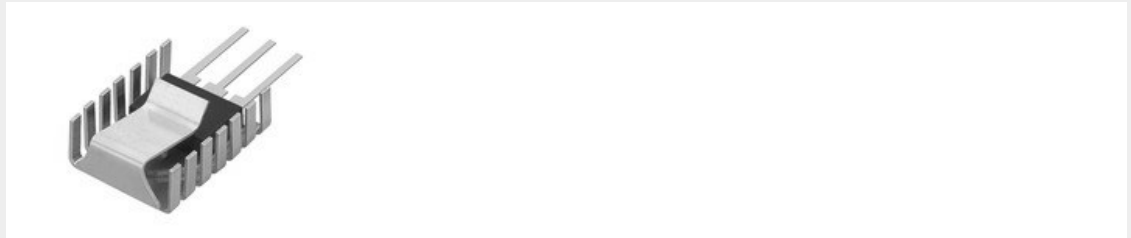
Board Level heatsinks

FK 245 MI 247 O

without soldering tag, for semiconductor-design TO 218, TO 220, TO 247

Data sheet

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Features

Technical Drawing

Service

Accessories / related products

material	copper (Cu)
for transistor	TO 218 TO 220 TO 247 TO 248 SIP-Multiwatt
width	20 mm
height	9 mm
length	27 mm
thermal resistance R_{th}	20.2 K/W
surface	solderable surface
version	without solder lug
material thickness	0.6 mm